

9.50-10.50GHz 4-Watt Internally-Matched Power FET

FEATURES

- 9.50-10.50GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 7.5 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}





Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (Ta = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 9.50-10.50GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	35.5	36.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 9.50-10.50GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	6.5	7.5		dB
ΔG	Gain Flatness $f = 9.50-10.50GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ f = 9.50-10.50GHz		30		%
Id _{1dB}	Drain Current at 1dB Compression f = 9.50-10.50GHz		1200	1300	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10$ MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² $V_{DS} = 10$ V, $I_{DSQ} \approx 65\%$ IDSS $f = 10.50$ GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		2000	2500	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
lgf	Forward Gate Current	48mA	14.4mA	
lgr	Reverse Gate Current	-9.6mA	-2.4mA	
Pin	Input Power	36dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Tstg Storage Temperature		-65C to +175C	
Pt	Total Power Dissipation	25W	25W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

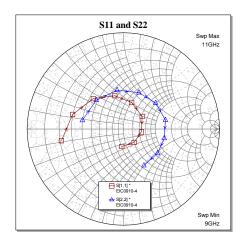
^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.

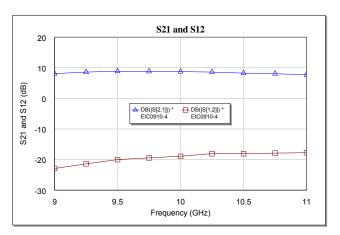


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PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50 Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} = 1100mA





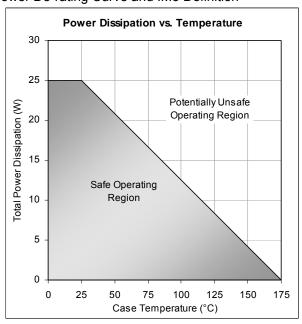
FREQ	S	11	S	S21 S12		12	S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
8.75	0.737	-144.630	2.269	-6.970	0.057	-49.810	0.470	-160.060
9.00	0.655	-169.280	2.531	-33.010	0.071	-78.500	0.435	168.080
9.25	0.549	164.010	2.683	-59.860	0.085	-105.960	0.411	133.320
9.50	0.444	134.710	2.765	-86.790	0.100	-134.450	0.408	99.190
9.75	0.357	104.470	2.755	-112.980	0.106	-161.110	0.411	66.750
10.00	0.289	72.550	2.727	-137.970	0.113	174.650	0.431	38.790
10.25	0.235	33.570	2.687	-163.320	0.124	150.320	0.447	11.850
10.50	0.191	-9.260	2.581	172.160	0.124	124.660	0.437	-12.860
10.75	0.179	-51.300	2.519	148.030	0.127	101.940	0.436	-35.330
11.00	0.182	-94.880	2.427	123.370	0.129	78.470	0.436	-60.600
11.25	0.183	-136.850	2.332	98.400	0.131	53.300	0.431	-86.500

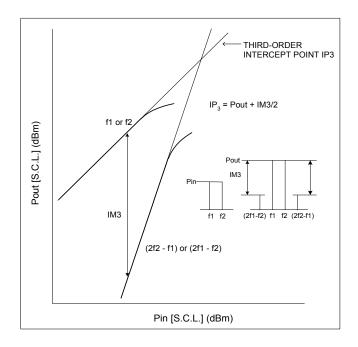
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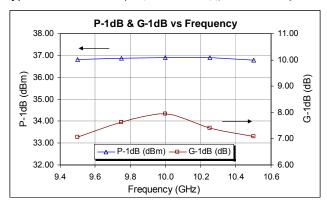
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Power De-rating Curve and IM3 Definition

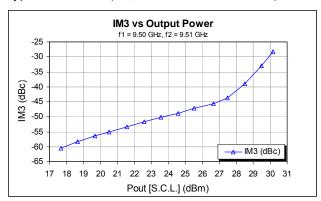




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 1100 mA)



Typical IM3 Data (V_{DS} = 10 V, I_{DSQ} ≈ 65% IDSS)



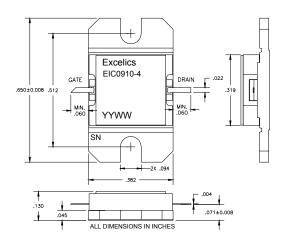


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PACKAGES OUTLINE

Dimensions in inches, Tolerance ± .005 unless otherwise specified

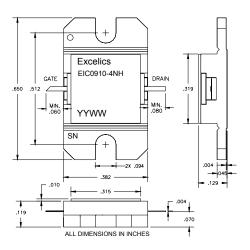
EIC0910-4 (Hermetic)





Caution! ESD sensitive device.

EIC0910-4NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC0910-4	Hermetic	Industrial	9.50-10.50GHz	35.5	-43
EIC0910-4NH	Non-Hermetic	Industrial	9.50-10.50GHz	35.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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